

01-17-2001

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U.S. PTO
09/752563
01/03/01

To the Honorable Commissioner of Patents and Trademarks:
Please record the attached original documents or copies thereof.

1. Name(s) of conveying party(ies):

Takahiro SAITO

2. Name(s) and Address(es) of receiving party(ies):

Disco Corporation
14-3, Higashi Kojiya 2-chome
Ota-ku, Tokyo144-8650
JAPAN

3. Nature of conveyance: Assignment
Execution Date: December 18, 2000

4A. Patent Application No.(s): To Be Assigned
Application execution date : January 3, 2001
4B. Patent No.(s):

5. Name and Address of Party to whom correspondence regarding this document should be mailed:

SMITH, GAMBRELL & RUSSELL, LLP
Beveridge, DeGrandi, Weilacher & Young
Intellectual Property Group
1850 M Street N.W. (Suite 800)
Washington, DC 20036

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202 659-2811

6. Total number of applications and patents involved : one

7. Total fee: \$40.00.
(Enclosed. Please charge any deficiency or refund any excess to counsel's deposit account.)

8. Deposit account no.: 02-4300

DO NOT USE THIS SPACE

9. Statement and Signature: To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.

Name of Person Signing : Michael A. Makuch, Reg. No. 32,263

Signature:
Date: January 3, 2001

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02 FC:581

40.00 00

Assignment

In consideration of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned, Takahiro SAITO, a citizen of Japan, residing at Tokyo, Japan.

Hereby sell, assign and transfer to Disco Corporation
a corporation of Japan having a place of business at 14 - 3, Higashi Kojiya 2 - chome, Ota - ku, Tokyo
144 - 8650 Japan

its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith December 18, 2000, and is entitled METHOD OF CUTTING CSP SUBSTRATES

, and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: December 18, 2000

TAKAHIRO SAITO (L.S.)

(L.S.)

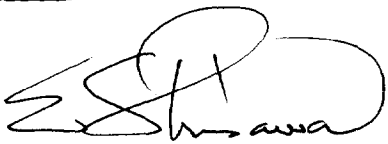
(L.S.)

Witness

(L.S.)

(L.S.)

(L.S.)



PATENT